

**AMENDMENTS TO THE CLAIMS:**

Please amend the claims as follows:

1. - 3. (Canceled)

4. (Previously presented) An outgas collection method comprising the steps of:

holding, within an exposure chamber under vacuum, a substrate on which surface a resist film is formed;

irradiating said resist film with an electron beam; and

collecting an outgas released from said resist film when irradiated with said electron beam to prevent the outgas from absorbing the energy of the electron beam.

5. (Previously presented) An outgas analysis method comprising the steps of:

holding, within an exposure chamber under vacuum, a substrate on which surface a resist film is formed;

irradiating said resist film with an electron beam; and

collecting an outgas released from said resist film when irradiated with said electron beam to prevent the outgas from absorbing the energy of the electron beam; and

analyzing a constituent of said collected outgas.

6. (Previously presented) An outgas analysis method comprising the steps of:

holding, within an exposure chamber under vacuum, a substrate on which surface a resist film is formed;

irradiating said resist film with an electron beam; and

analyzing a constituent of outgas released from said resist film when irradiated

with said electron beam.

7. (Cancelled)

8. (Currently amended) An electron beam aligner comprising:  
a substrate holder provided within an exposure chamber under vacuum, and for holding a substrate on which surface a resist film is formed; and

an electron beam irradiation unit means for irradiating which irradiates said resist film with an electron beam,

wherein the exposure chamber is constructed such that an outgas, released from said resist film during irradiation with said electron beam, is collected in order to prevent the outgas from absorbing the energy of the electron beam.

9. (Previously presented) The electron beam aligner of claim 8, further comprising a gas analysis means for analyzing a constituent of said collected outgas.

10. (Currently amended) An electron beam aligner comprising:  
a substrate holder provided within an exposure chamber under vacuum, and for holding a substrate on which surface a resist film is formed; and

an electron beam irradiation unit means for irradiating which irradiates said resist film with an electron beam,

wherein the exposure chamber is constructed such that an outgas, released from said resist film when irradiated with said electron beam, is collected and analyzed in order to prevent the outgas from absorbing the energy of the electron beam and to analyze the constituents of the collected outgas.